



TARGET THICKNESS: 0.125"
NUMBER OF LAYERS: 08

MULTILAYER PCB CONSTRUCTION SHEET

If there are max thickness requirements beyond +/- .10% overall - non-standard construction should be ordered and notes added.

8 Layer StackUp (0.125") L08-125-1ozHoz		Thickness (inches)
Layer 1	.5 oz foil plated to approximate* thickness 0.0017"	0.0017
Prepreg	Bonding ply (2x2116) Average Dielectric Constant 4.5	0.0084
Layer 2	1 oz foil thickness	0.0014
Core	Laminate Core Average Dielectric Constant 4.5	0.028
Layer 3	1 oz foil thickness	0.0014
Prepreg	Bonding ply (1x2116, 1x1080) Average Dielectric Constant 4.5	0.0064
Layer 4	1 oz foil thickness	0.0014
Core	Laminate Core Average Dielectric Constant 4.5	0.028
Layer 5	1 oz foil thickness	0.0014
Prepreg	Bonding ply (1x2116, 1x1080) Average Dielectric Constant 4.5	0.0064
Layer 6	1 oz foil thickness	0.0014
Core	Laminate Core Average Dielectric Constant 4.5	0.028
Layer 7	1 oz foil thickness	0.0014
Prepreg	Bonding ply (2x2116) Average Dielectric Constant 4.5	0.0084
Layer 8	.5 oz foil plated to approximate* thickness 0.0017"	0.0017
"Thickness does not include soldermask or surface finish"		0.1254

NOTES: